



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-07-19
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	K1Q7*U338AA6	A	SH1A	2018-07-19
	Amount	UoM	Unit type	ST ECOPACK Grade
	150	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	3.9x9.9x1.25	16	gull wing	
Comment	Q7 SO 16 .15 TO JEDEC MS-012; MDF valid for L6599ATDTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
;				
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	K1Q7*U338AA6				5000001.0	999990.0	
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	M-011 Other inorganic materials	5.526	mg	supplier	die	Silicon (Si)	7440-21-3		5.396	mg	976475	35973	
				supplier	metallization	Aluminium (Al)	7429-90-5		0.008	mg	1448	53	
				supplier	Passivation	Silicon Nitride	12033-89-5		0.035	mg	6334	233	
				supplier	Passivation	Silicon Oxide	7631-86-9		0.048	mg	8686	320	
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	543	20	
				supplier	back side metallization	Gold (Au)	7440-57-5		0.008	mg	1448	53	
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.028	mg	5067	187	
Leadframe	M-004 Copper and its alloys	35.844	mg	supplier	alloy	Copper (Cu)	7440-50-8		33.855	mg	944510	225700	
				supplier	alloy	Iron (Fe)	7439-89-6		0.796	mg	22207	5307	
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.048	mg	1339	320	
				supplier	alloy	Zinc (Zn)	7440-66-6		0.042	mg	1172	280	
				supplier	metallization	Nickel (Ni)	7440-02-0		0.086	mg	2399	573	
	M-008 Precious metals	supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	84	20			
	M-008 Precious metals	supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	112	27			
	supplier	metallization	Silver (Ag)	7440-22-4		1.010	mg	28178	6733				
	Die attach	M-015 Other organic materials	1.481	mg	supplier	glue	Silver (Ag)	7440-22-4		1.299	mg	877110	8660
					supplier	glue	Isobornyl Methacrylate	7534-94-3		0.074	mg	49966	493
supplier					glue	Acrylate resin	5888-33-5		0.074	mg	49966	493	
supplier					glue	Methyl acrylate polymer	87320-05-6		0.030	mg	20257	200	
supplier					glue	Epoxy(1,4-cyclohexylenedimethylolpropanediol)trimethoxysilane	3388-04-3		0.002	mg	1350	13	
supplier					glue	Tert-Butyl peroxy(2-ethyl)-hexanoate	3006-82-4		0.002	mg	1350	13	
supplier					wire	Copper (Cu)	7440-50-8		0.068	mg	100000	453	
Encapsulation	M-011 Other inorganic materials	107.080	mg	supplier	mold compound	Silica, vitreous	60676-86-0		93.910	mg	877008	626067	
				supplier	mold compound	Epoxy resin	85954-11-6		4.283	mg	39998	28553	
				supplier	mold compound	Epoxy	29690-82-2		4.283	mg	39998	28553	
				supplier	mold compound	phenol resin	25068-38-6		3.212	mg	29996	21413	
				supplier	mold compound	additive	Proprietary		1.071	mg	10002	7140	
				supplier	mold compound	carbon black	1333-86-4		0.321	mg	2998	2140	